Vishay Semiconductors

High Voltage Surface Mount Input Rectifier Diode, 8 A



PRODUCT SUMMARY							
Package	TO-252AA (D-PAK)						
I _{F(AV)}	8 A						
V _R	800 V, 1200 V						
V_F at I_F	1.1 V						
I _{FSM}	150 A						
T _J max.	150 °C						
Diode variation	Single die						

FEATURES

- · Glass passivated pellet chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Input rectification
- Vishay Semiconductors switches and output rectifiers which are available in identical package outlines

DESCRIPTION

The 8EWS..SPbF rectifier high voltage series has been optimized for very low forward voltage drop, with moderate leakage. The glass passivation technology used has reliable operation up to 150 °C junction temperature.

The high reverse voltage range available allows design of input stage primary rectification with outstanding voltage surge capability.

OUTPUT CURRENT IN TYPICAL APPLICATIONS									
APPLICATIONS	SINGLE-PHASE BRIDGE	THREE-PHASE BRIDGE	UNITS						
NEMA FR-4 or G10 glass fabric-based epoxy with 4 oz. (140 µm) copper	1.2	1.6							
Aluminum IMS, R _{thCA} = 15 °C/W	2.5	2.8	А						
Aluminum IMS with heatsink, $R_{thCA} = 5 \text{ °C/W}$	5.5	6.5							

Note

T_A = 55 °C, T_J = 125 °C, footprint 300 mm²

MAJOR RATINGS AND CHARACTERISTICS									
SYMBOL	CHARACTERISTICS	VALUES	UNITS						
I _{F(AV)}	Sinusoidal waveform at $T_C = 116 \ ^{\circ}C$	8	A						
V _{RRM}		800/1200	V						
I _{FSM}		150	A						
V _F	8 A, T _J = 25 °C	1.10	V						
TJ		-55 to +150	°C						

VOLTAGE RATINGS									
PART NUMBER	V _{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V _{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I _{RRM} AT 150 °C mA						
8EWS08SPbF	800	900	0.5						
8EWS12SPbF	1200	1300	0.5						

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VS-8EWS..SPbF Series



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ABSOLUTE MAXIMUM RATINGS								
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS				
Maximum average forward current	I _{F(AV)}	T_C = 105 °C, 180° conduction half sine wave	8					
Maximum peak one cycle	I _{FSM}	10 ms sine pulse, rated V_{RRM} applied	125	А				
non-repetitive surge current		10 ms sine pulse, no voltage reapplied	150					
Maximum I ² t for fusing	l ² t	10 ms sine pulse, rated V _{RRM} applied	78	A ² s				
Maximum Ft for fusing	1-1	10 ms sine pulse, no voltage reapplied	110	A-s				
Maximum I ² \sqrt{t} for fusing	l²√t	t = 0.1 ms to 10 ms, no voltage reapplied	1100	A²√s				

ELECTRICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CO	TEST CONDITIONS						
Maximum forward voltage drop	V _{FM}	8 A, T _J = 25 °C	1.1	V					
Forward slope resistance	r _t	T _{.1} = 150 °C	20	mΩ					
Threshold voltage	V _{F(TO)}	1j = 150 C	0.82	V					
Maximum rayaraa laakaga aurrant		$T_J = 25 \ ^\circ C$	V - Roted V	0.05	mA				
Maximum reverse leakage current	IRM	T _J = 150 °C	V _R = Rated V _{RRM}	0.50					

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C
Maximum thermal resistance, junction to case	R _{thJC}	DC operation	2.5	°O (M)
Typical thermal resistance, junction to ambient (PCB mount)	R _{thJA (1)}		62	°C/W
Annyovimete weight			1	g
Approximate weight			0.03	oz.
Marking device		Case style TO-252AA (D-PAK)	8EWS12S	

Note

⁽¹⁾ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 µm) copper 40 °C/W For recommended footprint and soldering techniques refer to application note #AN-994





Fig. 1 - Current Rating Characteristics



Fig. 2 - Current Rating Characteristics



Fig. 3 - Forward Power Loss Characteristics

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Fig. 4 - Forward Power Loss Characteristics



Half Cycle Current Pulses (N)





Fig. 6 - Maximum Non-Repetitive Surge Current

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Fig. 7 - Forward Voltage Drop Characteristics



Fig. 8 - Thermal Impedance ZthJC Characteristics





LINKS TO RELATED DOCUMENTS							
Dimensions	www.vishay.com/doc?95016						
Part marking information	www.vishay.com/doc?95059						
Packaging information	www.vishay.com/doc?95033						



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D-PAK (TO-252AA)

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INC	HES	NOTES	NOTES	SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STIVIDOL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STIVIDUL	MIN.	MAX.	MIN.	MAX.	NOTES
А	2.18	2.39	0.086	0.094			е	2.29	BSC	0.090	BSC	
A1	-	0.13	-	0.005			Н	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035			L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045			L1	2.74	BSC	0.108	REF.	
b3	4.95	5.46	0.195	0.215	3		L2	0.51	BSC	0.020	BSC	
С	0.46	0.61	0.018	0.024			L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035			L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5		L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3		Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5		Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3		Ø2	25°	35°	25°	35°	

Notes

⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994

(2) Lead dimension uncontrolled in L5

⁽³⁾ Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad

(4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip

(5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

⁽⁶⁾ Dimension b1 and c1 applied to base metal only

⁽⁷⁾ Datum A and B to be determined at datum plane H

⁽⁸⁾ Outline conforms to JEDEC outline TO-252AA

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